

## Configuration report for FS26-D OTP program ID: B2 rev A

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Rev. 1.0 - 23/05/2024

Report

Datasheet Revision 1.0

### 1 General description

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The FS26 is a Power System Basis Chip (Power SBC) designed for low and mid-end Microcontrollers Units (MCU). It features advanced power management conversion to support battery voltage from 3.2 V up to 40 V.

System level power is provided with a high-efficiency buck regulator, two programmable LDOs, a high-precision voltage reference and two voltage trackers with high-voltage protection to support off-module loads.

The FS26 features an independent and configurable functional Failsafe state machine with up to two integrated fail-safe outputs and system-level monitoring mechanisms to achieve a high-integrity safety level targeting systems up to ASIL D. Electrical specifications are detailed in the FS26 datasheet

### 2 Features and benefits

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- High-voltage boost controller supporting front-end or independent operation (VBST)
- One high-voltage buck pre-regulator with low power mode support (VPRE)
- One high-efficiency buck regulator for MCU core voltage support (VCORE)
- Two linear regulators with low power mode support (LDO1/2)
- High-precision accurate voltage reference ( $V_{REF} \pm 0.75\%$ )
- Two Voltage tracking regulators with high voltage protection for off-module load support (TRK1/2)
- Independent Failsafe state machine with monitoring mechanism targeting ASIL-D applications
- Long duration timer, counting up to 6 months with 1.0 s resolution
- Selectable wake-up sources to bring the system back from low power modes
- Two configurable GPIO pins (GPIO1/2)
- 10 MHz SPI communication interface

### 3 Applications

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- Automotive motor control / gate driver systems
- 48 V battery systems
- Hybrid battery systems
- Electric vehicle battery systems
- Body controller systems



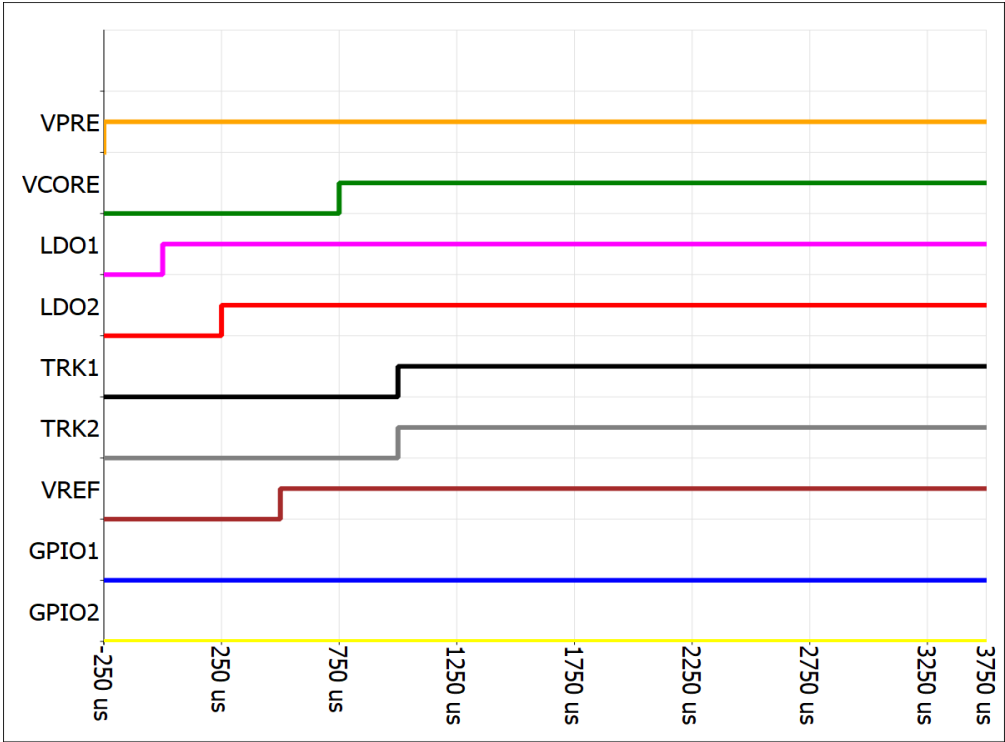
4 Ordering information

Table 1. Ordering information

Type number <sup>[1]</sup>	Package		
	Name	Description	Version
MFS2633AMDB2AD	LQFP48 AE	HLQFP48-EP plastic thermally enhanced low profile quad flat package. 48 terminals; 0.5mm pitch; 7 mm x 7 mm x 1.4 mm body	SOT1571-1

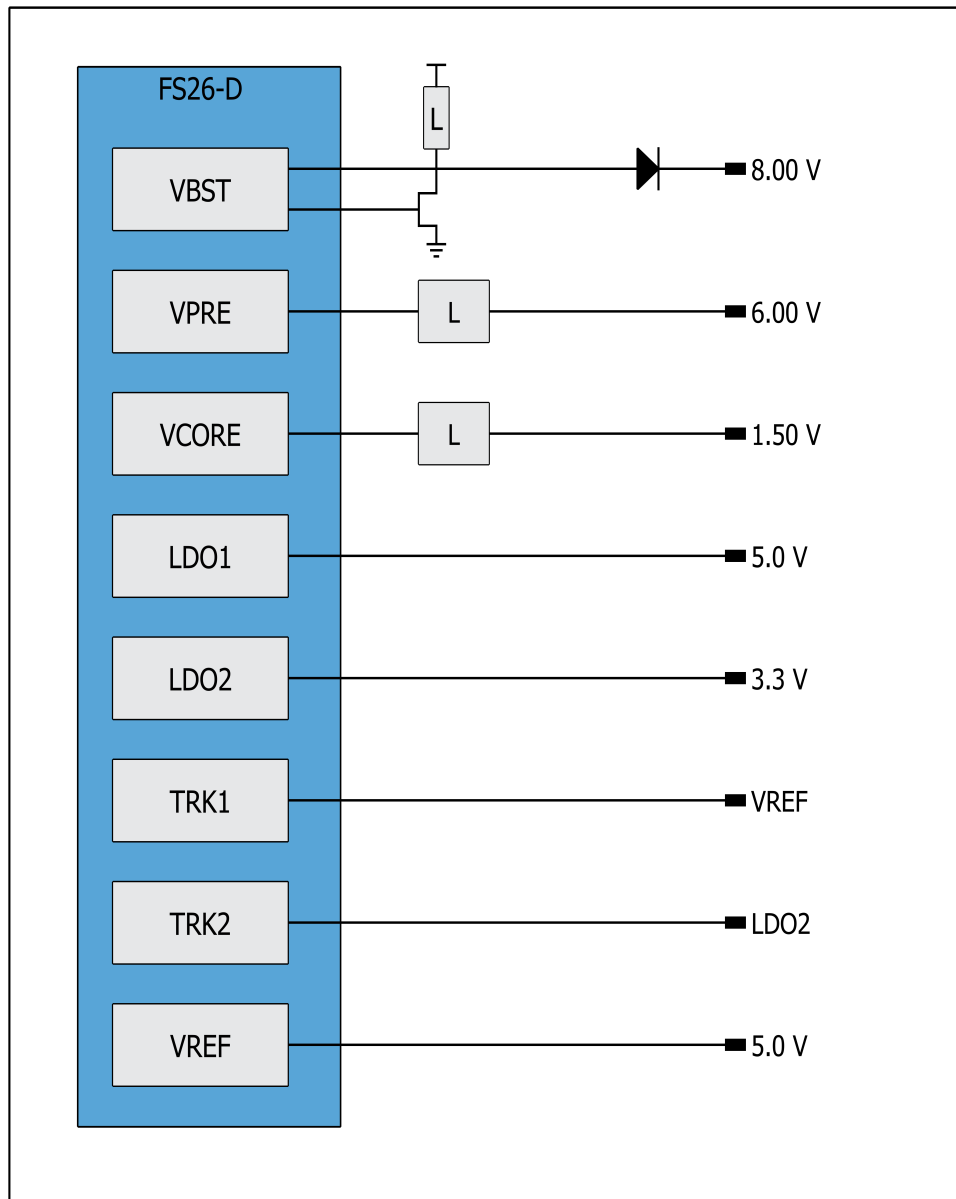
[1] To order parts in tape and reel, add the R2 suffix to the part number.

5 Power-up sequence summary



The signals depicted above are enable signals for each regulator. They don't represent the actual ramp up voltage.

## 6 Hardware configuration diagram



## 7 OTP configuration

See FS26 datasheet for parametric details. The OTP configuration summary for B2 sequence ID is provided in tables below.

**Table 2. Device OTP configuration**

Functional block	Feature	OTP selection
System configuration	VSUP UV Threshold	4.8 V/4.3 V
	Exit DFS On WAKE1 Event	DFS Exit on Wake1 Event Enabled
	Auto-retry Power Up From DFS	Auto-retry Enabled
	Auto-retry Mode	Infinite retry
	Auto-retry Timer Limit	800 ms
	Clock Frequency Selection	18 MHz
	VBOS Input Selection	Auto Transition on VPRE_UVH
	VBST Clock Selection	450 kHz
Power-up Sequence	Power-up Slot Time	250 us
	Power-up Slot Bypass	Bypass slot 5 to 6
	VCORE Power-up Slot	Slot 3
	LDO1 Power-up Slot	Slot 0
	LDO2 Power-up Slot	Slot 1
	TRK1 Power-up Slot	Slot 4
	TRK2 Power-up Slot	Slot 4
	VREF Power-up Slot	Slot 2
	GPIO1 Power-up Slot	OFF
	GPIO2 Power-up Slot	OFF

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I/O Configuration	GPIO1 Configuration	GPIO1 configured as an Input
	GPIO1 Low Side Polarity	GPIO1 LS active high
	GPIO1 Pull-up	Pull-Up Disabled
	GPIO1 Pull-down	Pull-Down Enabled
	GPIO1 Detection Threshold	High voltage threshold
	GPIO1 TSD Pull-down	Pull-down enabled in TSD
	GPIO2 Configuration	High Side Driver
	GPIO2 Low Side Polarity	GPIO2 LS active high
	GPIO2 VCORE PGOOD	GPIO2 is driven by VCORE PGOOD
	GPIO2 Pull-up	Pull-Up Disabled
	GPIO2 Pull-down	Pull-Down Enabled
	GPIO2 Detection Threshold	Low voltage threshold
	WAKE1 Detection Threshold	Low voltage threshold
	WAKE2 Detection Threshold	Low voltage threshold
	WAKE1 Pull-down	Pull-Down Enabled
	WAKE2 Pull-down	Pull-Down Enabled
	WAKE1 Pull-down Selection	200 kOhm
	WAKE2 Pull-down Selection	200 kOhm

Table 3. Switching Regulators

Functional block	Feature	OTP selection
VPRE Configuration	VPRE In Normal Mode	6.00 V
	VPRE In Standby Mode	5.35 V

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	DVS Ramp Rate	11 mV/us
	VPRE Over Current Flag	2.2 A
	Over Current Deglitch	500 us
	Soft-start Ramp	538 us
	VPRE Power Down Delay	100 us
	VPRE Transition Voltage	5.35 V
	VPRE Phase Delay	No delay
	VPRE LX Slew Rate	Fast mode
	Transconductance Amp	15 us
	Comp Capacitance	12.0 pF
	Comp Resistance	1300 kOhm
	Slope Compensation	266 mV/us
	Minimum On Time In PFM	1125 ns
	Minimum Off Time In PFM	720 ns
	VPRE Clock Selection	FSW/40
	TSD Behavior	Go to DFS
	TSD Pull-down	Pull-down enabled in TSD
VBST Configuration	VBST Voltage	8.00 V
	VBST Configuration	Front-end boost
	VBSTFB OV Monitor Mode	Auto-enable mode
	Phase Delay	1 Clock Cycle
	Low-side Slew Rate	PU = 1.5 Ohm / PD = 1.0 Ohm

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	Minimum TON	200 ns
	VBST Soft Start	425 us
	Max Duty-cycle	87.50 %
	Comp Capacitance	200 pF
	Comp Transconductance	5.1 us
	Comp Resistance	250 kOhm
	Current Limit	150 mV/RSNS
	Slope Compensation	155 mV/us
VCORE Configuration	VCORE Voltage	1.50 V
	Control Type	Valley mode control
	Operating Mode	CCM only
	Soft Start	10 mV/us
	VCORE Current Limit	3.4 A
	Phase Delay	2 Clock Cycles
	High-side Slew Rate	Rise = 5 V/ns; Fall = 2.2 V/ns
	Transconductance Amp	26 us
	Comp Capacitance	50 pF
	Comp Resistance	200 kOhm
	VCORE Inductor	1 uH
	TSD Behavior	Go to DFS
	TSD Pull-down	Pull-down enabled in TSD

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Table 4. Regulators

Functional block	Feature	OTP selection
LDO1 configurations	LDO1 Voltage In Normal	5.0 V
	LDO1 Voltage In Standby	5.0 V
	LDO1 In Standby Mode	LDO1 Enabled
	TSD Behavior	LDO1 disabled only
	TSD Pull-down	Pull-down enabled in TSD
LDO2 configurations	LDO2 Voltage In Normal	3.3 V
	LDO2 Voltage In Standby	3.3 V
	LDO2 In Standby Mode	LDO2 Enabled
	TSD Behavior	LDO2 disabled only
	TSD Pull-down	Pull-down enabled in TSD
VREF configurations	VREF Voltage	5.0 V
	Internal LDO Reference	1.2 V
TRK1 configurations	TRK1 Input Selection	VREF
	TSD Behavior	TRK1 disabled only
	TSD Pull-down	Pull-down enabled in TSD
TRK2 configurations	TRK2 Input Selection	LDO2
	TSD Behavior	TRK2 disabled only
	TSD Pull-down	Pull-down enabled in TSD



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Table 5. Voltage Monitoring

Functional block	Feature	OTP selection
VMONPRE Configuration	VPRE Monitoring Voltage	6.00 V
	VPRE OV Threshold	110.0 %
	VPRE UV Threshold	90.0 %
	VMONPRE OV Deglitch	45 us
	VMONPRE UV Deglitch	40 us
VMONLDO1 Configuration	LDO1 Monitoring Voltage	5.0 V
	LDO1 OV Threshold	106.0 %
	LDO1 UV Threshold	94.0 %
	LDO1 Degraded UV Monitoring	Normal UV
	VMONLDO1 OV Deglitch	45 us
	VMONLDO1 UV Deglitch	40 us
	LDO1 Pin Lift Detection	LDO1 pin lift detection enabled
VMONTRK1 Configuration	TRK1 Monitoring Voltage	5.0 V
	TRK1 OV Threshold	105.0 %
	TRK1 UV Threshold	95.0 %
	VMONTRK1 OV Deglitch	45 us
	VMONTRK1 UV Deglitch	40 us
VMONCORE Configuration	VCORE Monitoring Voltage	1.50 V
	CORE OV Threshold	106.0 %

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	CORE UV Threshold	94.0 %
	VMONCORE OV Deglitch	45 us
	VMONCORE UV Deglitch	40 us
VMONLDO2 Configuration	LDO2 Monitoring Voltage	3.3 V
	LDO2 OV Threshold	106.0 %
	LDO2 UV Threshold	94.0 %
	LDO2 Degraded UV Monitoring	Normal UV
	VMONLDO2 OV Deglitch	45 us
	VMONLDO2 UV Deglitch	40 us
	LDO2 Pin Lift Detection	LDO2 pin lift detection enabled
VMONTRK2 Configuration	TRK2 Monitoring Voltage	3.3 V
	TRK2 OV Threshold	105.0 %
	TRK2 UV Threshold	95.0 %
	VMONTRK2 OV Deglitch	45 us
	VMONTRK2 UV Deglitch	40 us
VMONEXT Configuration	External VMON OV Threshold	110.0 %
	External VMON UV Threshold	90.0 %
	VMONEXT OV Deglitch	45 us
	VMONEXT UV Deglitch	40 us
VMONREF Configuration	VREF Monitoring Voltage	5.0 V
	VREF OV Threshold	104.5 %

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	VREF UV Threshold	95.5 %
	VMONREF OV Deglitch	45 us
	VMONREF UV Deglitch	40 us
	VREF Pin Lift Detection	VREF pin lift detection enabled

Table 6. System Safety Configuration

Functional block	Feature	OTP selection
ABIST1 Configuration	ABIST1 On VMONPRE	ABIST1 Enabled
	ABIST1 On VMONCORE	ABIST1 Enabled
	ABIST1 On VMONLDO1	ABIST1 Enabled
	ABIST1 On VMONLDO2	ABIST1 Enabled
	ABIST1 On VMONTRK1	ABIST1 Disabled
	ABIST1 On VMONTRK2	ABIST1 Disabled
	ABIST1 On VMONREF	ABIST1 Enabled
	ABIST1 On VMONEXT	ABIST1 Disabled
System Safety Configuration	DFS Entry Mode	Go to DFS when FLT_ERR_CNT = max
	FS1B Assertion Mode	Delayed Assertion Enabled
	RSTB Delay From FS0B	0 us
	RSTB Low Detection Timer	8 Second Timer Enabled
	Watchdog Timer	WD Timer Enable
	Bypass LBIST From Standby	Always perform LBIST
	Main DFS Availability	Deep Fail Safe Available
	Deep Failsafe State Availability	Deep Fail Safe Available

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Table 7. OTP ID

Functional block	Feature	OTP selection
OTP Program ID	Program ID High	B
	Program ID Low	2
Main Version Bits	LDO2 Regulator	LDO2 available
	VCORE Regulator	CORE available
	TRK1 Regulator	TRK1 available
	TRK2 Regulator	TRK2 available
	VREF Regulator	VREF available
	VBST Regulator	VBST available
	GPIO1 Pin	GPIO1 available
	GPIO2 Pin	GPIO2 available
	LDT Function	LDT available
	TWARN Selection	155 °C
	VCORE Max Current	1650 mA
	Device ID	0x20
FS Versioning Bits	VPRE Monitor	VMON Enabled
	VCORE Monitor	VMON Enabled
	LDO1 Monitor	VMON Enabled
	LDO2 Monitor	VMON Enabled
	TRK1 Monitor	VMON Enabled
	TRK2 Monitor	VMON Enabled

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	VREF Monitor	VMON Enabled
	External Monitor	VMON Disabled
	FCCU Function	FCCU available
	Fault Recovery Function	Fault Recovery available
	Watchdog Type	Challenger WD
	FS1B Type	FS1B available
	ABIST On-demand	ABIST2 available
	Cyclic OTP Check	CORRUPT available
	ERRMON Function	ERRMON not available
	LBIST Operation	LBIST available

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